

### General Description

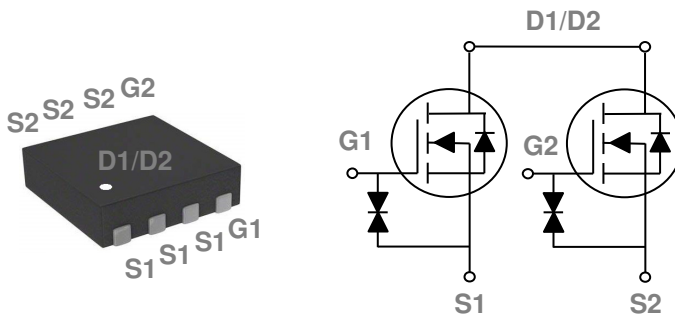
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

|       |       |     |
|-------|-------|-----|
| BVDSS | RDSON | ID  |
| 20V   | 8mΩ   | 24A |

### Features

- 20V,24A,  $R_{DS(ON)} = 8m\Omega @ V_{GS} = 4.5V$
- Improved  $dv/dt$  capability
- Fast switching
- G-S ESD Protection Diode Embedded
- Green Device Available

### DFN3x3 Dual Pin Configuration



### Applications

- Handheld Instruments
- POL Applications
- Battery Protection Applications

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol    | Parameter  | Rating     | Units               |
|-----------|--|------------|---------------------|
| $V_{DS}$  | Drain-Source Voltage                                   | 20         | V                   |
| $V_{GS}$  | Gate-Source Voltage                                    | $\pm 12$   | V                   |
| $I_D$     | Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )  | 24         | A                   |
|           | Drain Current – Continuous ( $T_c=100^\circ\text{C}$ ) | 15         | A                   |
| $I_{DM}$  | Drain Current – Pulsed <sup>1</sup>                    | 96         | A                   |
| $P_D$     | Power Dissipation ( $T_c=25^\circ\text{C}$ )           | 27         | W                   |
|           | Power Dissipation – Derate above $25^\circ\text{C}$    | 0.22       | W/ $^\circ\text{C}$ |
| $T_{STG}$ | Storage Temperature Range                              | -55 to 150 | $^\circ\text{C}$    |
| $T_J$     | Operating Junction Temperature Range                   | -55 to 150 | $^\circ\text{C}$    |

### Thermal Characteristics

| Symbol          | Parameter                              | Typ. | Max. | Unit                      |
|-----------------|--|------|------|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | ---  | 62   | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to case    | ---  | 4.55 | $^\circ\text{C}/\text{W}$ |

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

| Symbol            | Parameter                      | Conditions  | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|---|------|------|------|------|
| BV <sub>DSS</sub> | Drain-Source Breakdown Voltage | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                      | 20   | ---  | ---  | V    |
| I <sub>DSS</sub>  | Drain-Source Leakage Current   | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C | ---  | ---  | 1    | μA   |
|                   |                                | V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C | ---  | ---  | 10   | μA   |
| I <sub>GSS</sub>  | Gate-Source Leakage Current    | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V                      | ---  | ---  | ±20  | μA   |

**On Characteristics**

|                     |  |  |     |      |      |    |
|---------------------|--|--|-----|------|------|----|
| R <sub>DS(ON)</sub> | Static Drain-Source On-Resistance <sup>3</sup> | V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.4A              | --- | 6.7  | 8    | mΩ |
|                     |  | V <sub>GS</sub> =4.0V, I <sub>D</sub> =2.4A              | --- | 7.1  | 8.5  | mΩ |
|                     |  | V <sub>GS</sub> =3.7V, I <sub>D</sub> =2.4A              | --- | 7.3  | 9    | mΩ |
|                     |  | V <sub>GS</sub> =3.1V, I <sub>D</sub> =2.4A              | --- | 8    | 10.5 | mΩ |
|                     |  | V <sub>GS</sub> =2.5V, I <sub>D</sub> =2.4A              | --- | 9.2  | 12   | mΩ |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA | 0.5 | 0.65 | 1.5  | V  |
| g <sub>fs</sub>     | Forward Transconductance                       | V <sub>DS</sub> =5V, I <sub>D</sub> =5A                  | --- | 15   | ---  | S  |

**Dynamic and switching Characteristics**

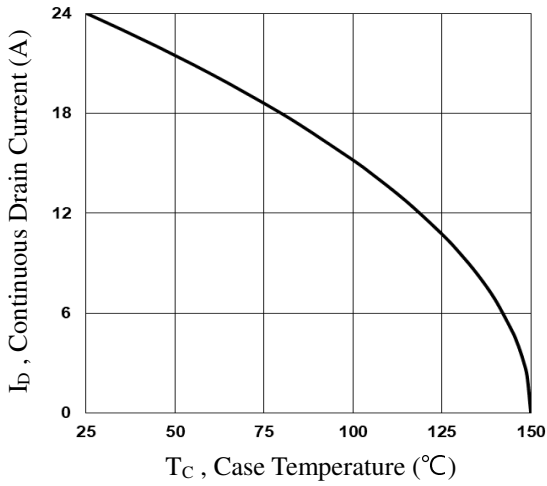
|                     |                                    |  |     |      |     |    |
|---------------------|------------------------------------|--|-----|------|-----|----|
| Q <sub>g</sub>      | Total Gate Charge <sup>2,3</sup>   | V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A                      | --- | 13.8 | --- | nC |
| Q <sub>gs</sub>     | Gate-Source Charge <sup>2,3</sup>  |  | --- | 2.1  | --- |    |
| Q <sub>gd</sub>     | Gate-Drain Charge <sup>2,3</sup>   |  | --- | 4.5  | --- |    |
| T <sub>d(on)</sub>  | Turn-On Delay Time <sup>2,3</sup>  | V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω<br>I <sub>D</sub> =5A | --- | 28   | --- | ns |
| T <sub>r</sub>      | Rise Time <sup>2,3</sup>           |  | --- | 64   | --- |    |
| T <sub>d(off)</sub> | Turn-Off Delay Time <sup>2,3</sup> |  | --- | 60   | --- |    |
| T <sub>f</sub>      | Fall Time <sup>2,3</sup>           |  | --- | 55   | --- |    |
| C <sub>iss</sub>    | Input Capacitance                  | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz                                    | --- | 1514 | --- | pF |
| C <sub>oss</sub>    | Output Capacitance                 |  | --- | 178  | --- |    |
| C <sub>rss</sub>    | Reverse Transfer Capacitance       |  | --- | 145  | --- |    |

**Drain-Source Diode Characteristics and Maximum Ratings**

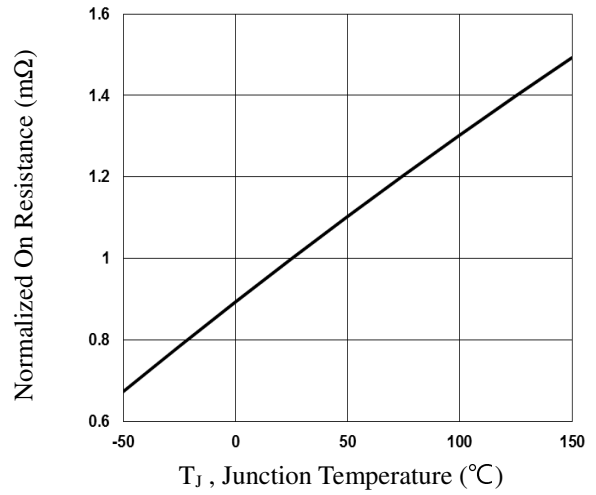
| Symbol          | Parameter                 | Conditions  | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current             | ---  | ---  | 24   | A    |
| I <sub>SM</sub> | Pulsed Source Current     |   | ---  | ---  | 48   | A    |
| V <sub>SD</sub> | Diode Forward Voltage     | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C | ---  | ---  | 1    | V    |

Note :

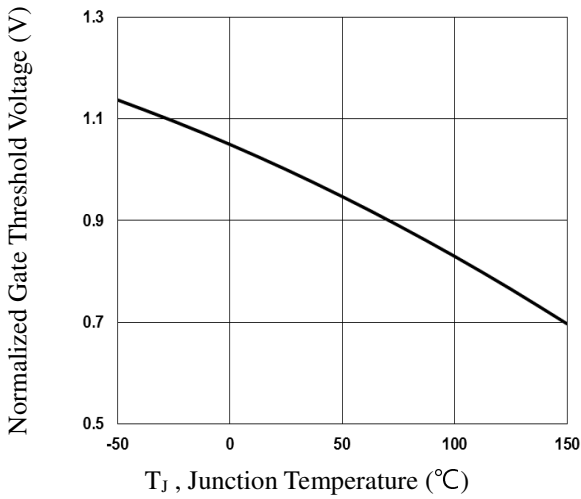
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



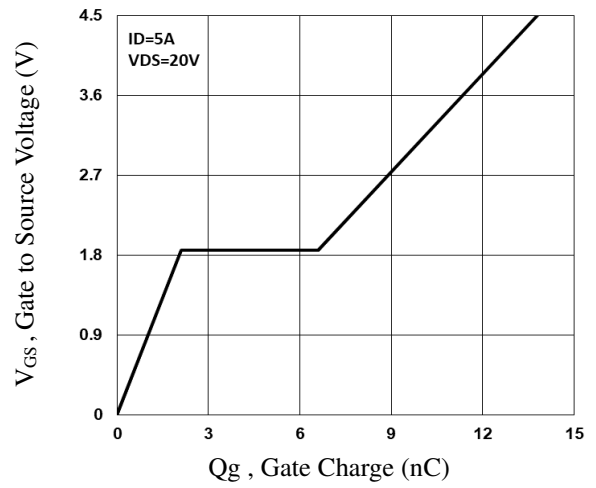
**Fig.1 Continuous Drain Current vs.  $T_C$**



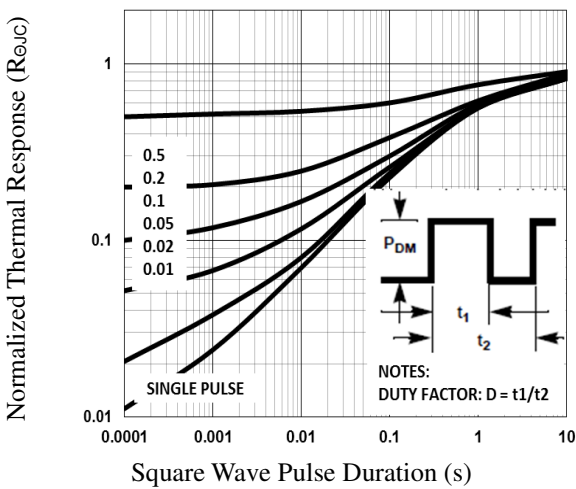
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



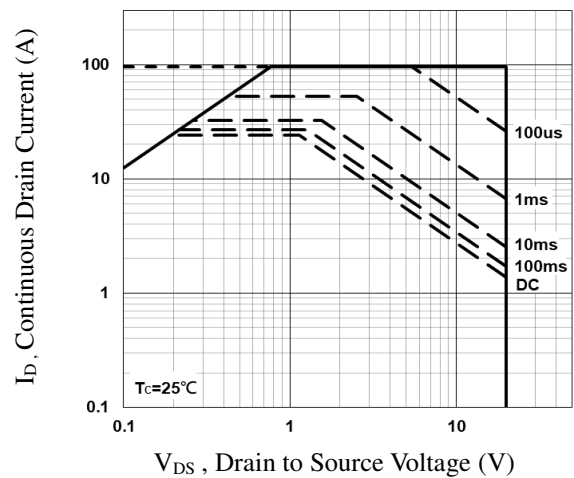
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



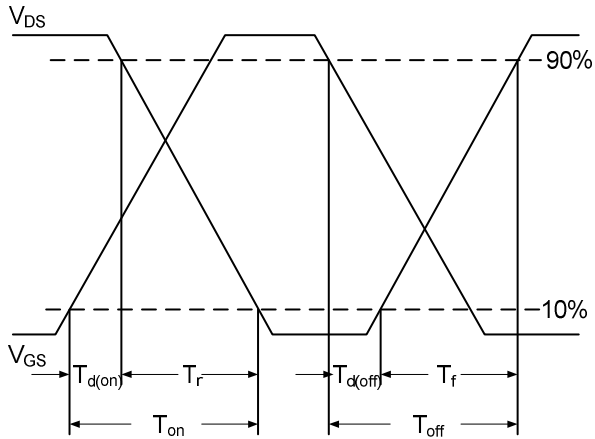
**Fig.4 Gate Charge Waveform**



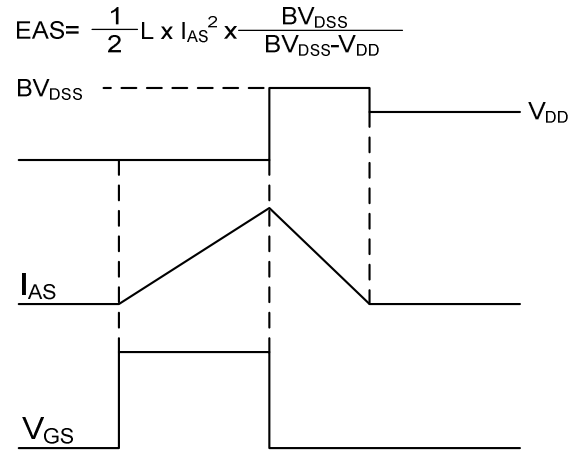
**Fig.5 Normalized Transient Response**



**Fig.6 Maximum Safe Operation Area**

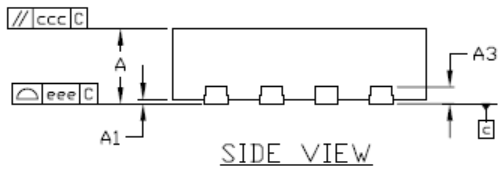
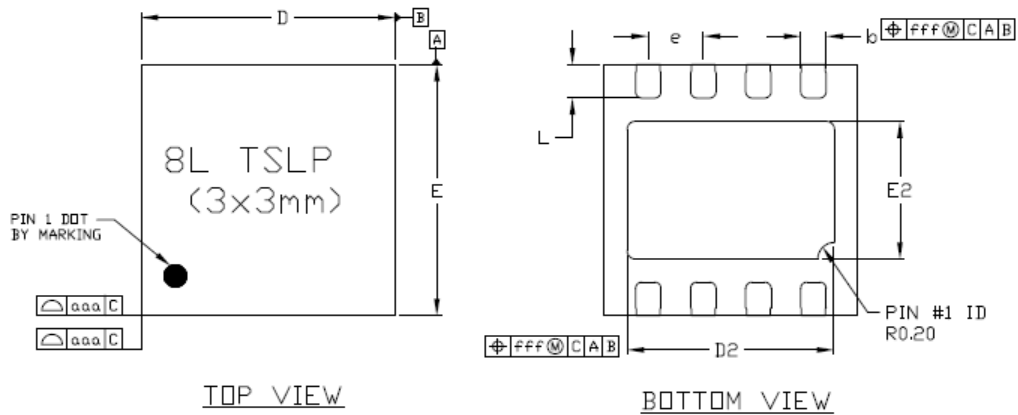


**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## DFN3x3 Dual PACKAGE INFORMATION



### Notes

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER JEDEC MO-220.

| Symbol | Dimensions In Millimeters |       |       |
|--------|---------------------------|-------|-------|
|        | Min                       | Nom   | Max   |
| A      | 0.700                     | 0.750 | 0.800 |
| A1     | -                         | -     | 0.050 |
| A3     | 0.203Ref.                 |       |       |
| D      | 2.950                     | 3.000 | 3.050 |
| E      | 2.950                     | 3.000 | 3.050 |
| D2     | 2.400                     | 2.450 | 2.500 |
| E2     | 1.600                     | 1.650 | 1.700 |
| b      | 0.250                     | 0.300 | 0.350 |
| e      | 0.650BSC                  |       |       |
| L      | 0.350                     | 0.400 | 0.450 |
| aaa    | 0.010                     |       |       |
| bbb    | 0.010                     |       |       |
| ccc    | 0.010                     |       |       |
| ddd    | 0.050                     |       |       |
| eee    | 0.080                     |       |       |
| fff    | 0.100                     |       |       |